

# Torben Steegmann

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**Homepage:** [www.torbensteegmann.com](http://www.torbensteegmann.com)  
**GitHub:** <https://github.com/TorbenSteegmann>

## GENERAL INFORMATION

Date of birth: 04/18/2000  
Place of birth: Hong Kong  
Nationality: German

## TECHNICAL SKILLS

- Advanced knowledge of C++
- Physics simulation
- Graphics programming
- Proficient in most common languages like:
  - Java
  - Python
  - C

## SOFT SKILLS

- Strong interpersonal communication
- Teamworking skills
- Flexibility
- Desire to learn and improve
- Ambition

## PROJECTS

- Physics Simulations
  - Classical Dynamics
  - Quantum Dynamics
  - C++
- Game Development
  - OpenGL/C++
  - UE 5
- Ray Tracing Engine
  - C++
- Software Verification
  - C++

## CAREER OBJECTIVE

Dedicated, project-driven student with a strong passion for physics simulation and computer graphics. Eager to apply and enhance my skillset through real software applications. Excited about the prospect of learning from experts in the field and the opportunity to contribute to the creation and improvement of software.

## EDUCATION

- |                   |   |
|-------------------|---|
| 02/2025 – 06/2025 | ▪ <b>RWTH-Ambassador</b><br>Tsinghua University, China  |
| 10/2023 – 09/2025 | ▪ <b>M.Sc. Computer Science</b><br>RWTH Aachen University                                       |
| 04/2020 – 09/2023 | ▪ <b>B.Sc. Computer Science</b><br>RWTH Aachen University                                       |
| 10/2018 – 03/2020 | ▪ <b>B.Sc. Applied Computer Science</b><br>Ravensburg-Weingarten University of Applied Sciences |
| 07/2018           | ▪ <b>Abitur</b><br>Cornelius-Burgh-Gymnasium Erkelenz   |

## WORK EXPERIENCE

- |                   |  |
|-------------------|--|
| 04/2024 – 07/2024 | ▪ <b>Internship: Virtual Reality Lab</b> <ul style="list-style-type: none"><li>▪ Development of VR applications</li></ul>                                  |
| 10/2022 – 01/2023 | ▪ <b>Internship: Cyber-Physical Mobility Lab</b> <ul style="list-style-type: none"><li>▪ Implementation of an Autonomous Package Delivery System</li></ul> |